I. AMENDMENTS TO THE CLAIMS:

Please cancel claims 2, 21 and 22 without prejudice. Kindly amend claims 1, 11, 13, 16 and 20, and add new claims 23-26 as follows.

The following Listing of Claims replaces all prior Listings, or versions, of claims in the above-captioned application.

LISTING OF CLAIMS:

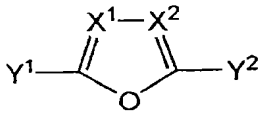
1. (Currently Amended) A photosensitive resin composition comprising:

(A) a binder polymer;

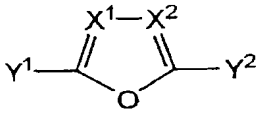
(B) a photopolymerizing compound with an ethylenic unsaturated bond;

(C) a photopolymerization initiator; and

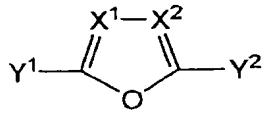
(D) a compound represented by the following general formula (1a), (1b), (1c), or (2),



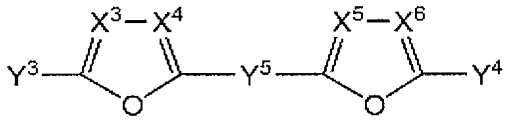
···(1a)



···(1b)



···(1c)



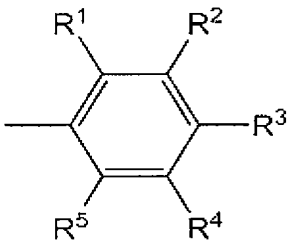
···(2)

wherein

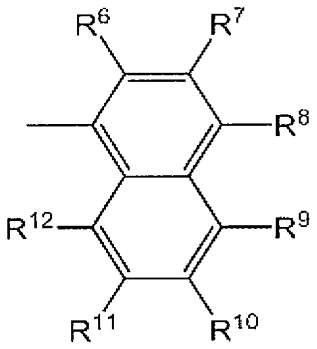
in formula (1a), X^1 represents a CH group, a CCH_3 group, a CC_2H_5 group, or nitrogen, X^2 represents a CH group, a CCH_3 group, or a CC_2H_5 group, and $Y^1$and Y^2 represent mutually different optionally substituted aryl;

in formula (1b), X^1 and X^2 both represent nitrogen, and $Y^1$and Y^2 represent mutually different optionally substituted aryl;

in formula (1c), X^1 and X^2 both represent nitrogen and $Y^1$and Y^2 both represent mutually the same group represented by formula (3) or formula (4)



···(3)



···(4)

wherein in formulae (3) and (4), at least one of R1, R2, R3, R4, R5, R6, R7, R8, R9, R10, R11, R12 represents C1-20 alkyl and the other represent hydrogen; and

in formula (2), X^3, X^4, X^5 and X^6 each independently represent a CH group, a CCH_3 group, a CC_2H_5 group or nitrogen, Y^3 and Y^4 each independently represent optionally substituted aryl, and Y^5 represents optionally substituted arylene,

wherein the acid value of component (A) is 45-200 mg KOH/g, and

wherein component (A) contains polymerizable monomer with a carboxyl group, (meth)acrylic acid alkyl esters, and styrene or a styrene derivative as a copolymerizing

component, component (B) contains a bisphenol A-type (meth)acrylate compound, and component (C) contains a 2,4,5-triarylimidazole dimer.

2. (Cancelled)

3. (Cancelled)

4. (Previously Presented) A photosensitive resin composition according to claim 1, wherein the weight-average molecular weight of component (A) is 20,000-300,000.

5. (Previously Presented) A photosensitive resin composition according to claim 1, wherein the component (A) content is 20-90 parts by weight, the component (B) content is 10-80 parts by weight, the component (C) content is 0.01-20 parts by weight and the component (D) content is 0.001-20 parts by weight, with respect to 100 parts by weight as the total of component (A) and component (B).

6. (Previously Presented) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 1 formed on the support.

7. (Previously Presented) A resist pattern forming method comprising the steps of:

laminating a photosensitive resin composition layer for a photosensitive element according to claim 6 on a circuit forming board;

irradiating prescribed sections of the photosensitive resin composition layer with active light rays for photocuring of exposed sections; and then

removing non-exposed sections.

8. (Previously Presented) A process for manufacturing a printed circuit board comprising the steps of etching or plating a circuit forming board having a resist pattern formed thereon by a resist pattern forming method according to claim 7.

9. (Cancelled)

10. (Cancelled)

11. (Currently Amended) A photosensitive resin composition according to claim 20~~claim 2~~, wherein the weight-average molecular weight of component (A) is 20,000-300,000.

12. (Cancelled)

13. (Currently Amended) A photosensitive resin composition according to claim 20~~claim 2~~, wherein the component (A) content is 20-90 parts by weight, the component (B) content is 10-80 parts by weight, the component (C) content is 0.01-20 parts by weight and the component (D) content is 0.001-20 parts by weight, with respect to 100 parts by weight as the total of component (A) and component (B).

14. (Cancelled)

15. (Previously Presented) A photosensitive resin composition according to claim 4, wherein the component (A) content is 20-90 parts by weight, the component (B) content is 10-80 parts by weight, the component (C) content is 0.01-20 parts by weight and the component (D) content is 0.001-20 parts by weight, with respect to 100 parts by weight as the total of component (A) and component (B).

16. (Currently Amended) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 20~~claim 2~~ formed on the support.

17. (Cancelled)

18. (Previously Presented) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 4 formed on the support.

19. (Previously Presented) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 5 formed on the support.

20. (Currently Amended) A photosensitive resin composition comprising:

(A) a binder polymer;

(B) a photopolymerizing compound with an ethylenic unsaturated bond;

(C) a photopolymerization initiator; and

(D) one or more compounds selected from the group consisting of 2,5-diphenylfuran,

2,5-diphenyl-3,4-dimethylfuran, 2,5-diphenyl-3-ethylfuran, 2,5-di(p-methylphenyl)furan, 2,5-di(2,4-dimethylphenyl)furan, 2,5-di(p-butylphenyl)furan, 2,5-di(p-benzylphenyl)furan, 2-phenyl-5-(p-biphenylyl)furan, 2,5-di(p-biphenylyl)furan, 2-phenyl-5-(α-naphthyl)furan, 2,5-diphenyloxazole, 2,5-diphenyl-3-methyloxazole, 2,5-di(p-isopropylphenyl)oxazole, 1,4-bis(2-(5-phenyloxazolyl))benzene, 1,4-bis(2-(4-methyl-5-phenyloxazolyl))benzene, 2-phenyl-5-(p-biphenylyl)oxazole, 2-phenyl-5-(α-naphthyl)oxazole, 2,5-di(α-naphthyl)oxazole, 1,4-bis(2-(5-phenyloxazolyl))naphthalene, 2,5-di(α-naphthyl)-1,3,4-oxadiazole, 2-phenyl-5-(α-naphthyl)-1,3,4-oxadiazole, 2,5-di(p-t-butylphenyl)-1,3,4-oxadiazole, 2,5-di(4-methyl-1-naphthyl)-1,3,4-oxadiazole, 2-phenyl-5-(p-biphenylyl)-1,3,4-oxadiazole, 2-(4-biphenylyl)-5-(4-t-butylphenyl)-1,3,4-oxadiazole, and 1,4-bis(2-(5-phenyl-1,3,4-oxadiazolyl))benzene,

wherein the acid value of component (A) is 45-200 mg KOH/g, and

wherein component (A) contains polymerizable monomer with a carboxyl group, (meth)acrylic acid alkyl esters, and styrene or a styrene derivative as a copolymerizing component, component (B) contains a bisphenol A-type (meth)acrylate compound, and component (C) contains a 2,4,5-triarylimidazole dimer.

21. (Cancelled)

22. (Cancelled)

23. (NEW) A photosensitive resin composition according to Claim 1, wherein the component (C) contains 1.0 to 2.0 parts by weight of 2,4,5-triarylimidazole dimer, with respect to 100 parts by weight as the total of component (A) and component (B).

24. (NEW) A photosensitive resin composition according to Claim 1, wherein the component (A) contains 0.1 to 30 wt% of the styrene or styrene derivative as a copolymerizing component, with respect to the total amount of component (A).

25. (NEW) A resist pattern forming method that comprises the steps of:

laminating a photosensitive resin composition layer for a photosensitive element according to Claim 6 on a circuit forming board;

irradiating prescribed sections of the photosensitive resin composition layer with active light rays for photocuring of exposed sections; and

removing non-exposed sections by developing with 0.1 to 5.0 wt% of sodium carbonate dilute solution, or with 0.1 to 5.0 % wt% of potassium carbonate dilute solution, or with 0.1 to 5.0 % wt% of sodium hydroxide dilute solution.

26. (NEW) A process for manufacturing a printed circuit board that comprises the step of:

etching or plating a circuit forming board having a resist pattern formed thereon by a resist pattern forming method according to claim 25.